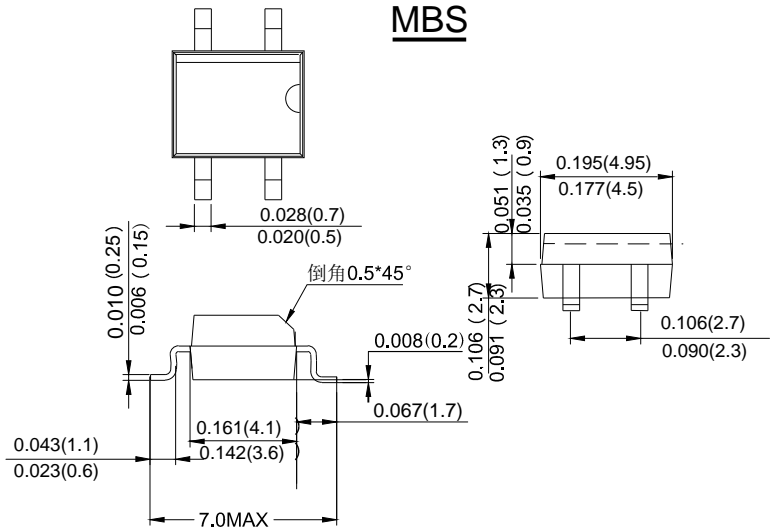


### Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-30A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

### Mechanical Data

- Case:Reliable low cost construction utilizing molded plastic technique
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number



dimensions in inches and (millimeters)

### Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.  
 Single Phase, half wave, 60Hz, resistive or inductive load.  
 For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	RMB1S	RMB2S	RMB4S	RMB6S	RMB8S	RMB10S	UNITS
Peak Repetitive Reverse Voltage	$V_{RRM}$							
Working Peak Reverse Voltage	$V_{RWM}$	100	200	400	600	800	1000	V
DC Blocking Voltage	$V_{DC}$							
RMS Reverse Voltage	$V_{RMS}$	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@ $T_A=40^\circ C$ (Note 2)@ $T_A=40^\circ C$	$I_o$	0.5 0.8						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30						A
Forward Voltage per element @ $I_F=0.8A$	$V_{FM}$	1.3						V
Peak Reverse Current @ $T_A=25^\circ C$ At Rated DC Blocking Voltage @ $T_A=125^\circ C$	$I_R$	5.0 500						$\mu A$
Maximum reverse recovery time (Note 3)	$T_{RR}$	150			250	500		ns
Typical Junction Capacitance per leg	$C_J$	13						pF
Typical Thermal Resistance per leg (Note 4)	$R_{\theta JA}$	70						°C/W
	$R_{\theta JL}$	20						
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55to+150						°C

- Note:1. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.  
 2. Mounted on aluminum substrate PC board with 1.3mm<sup>2</sup> solder pad.  
 3. Reverse Recovery Test Conditions:  $I_F=0.5A$ ,  $I_R=1A$ ,  $I_{rr}=0.25A$ .  
 4. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

